

Amendments to the Claims:

The **Listing of Claims** below replaces all prior versions, and listings, of Claims in the Application.

Listing of Claims:

Claims 1 – 20 (Previously cancelled).

Claims 21 – 36 (Cancelled). **Please cancel claims 21 – 36** and add the following new claims:

37. (new) A test apparatus for providing contact with a plurality of electrically conductive members of an electronic component, said test apparatus comprising:

a compressible housing adapted for having an electronic component including a plurality of electrically conductive members compressibly positioned therein, said compressible housing including a base and a cover and a compressible member positioned between said base and cover and between said cover and said electronic component when said electronic component is positioned within said compressible housing;

a base member including a plurality of compressible probes positioned therein, said base of said compressible housing being adapted for being positioned on said base member; and

structure for bringing said compressible housing having said electronic component therein and said base member together such that selected ones of said compressible probes engage respective ones of said electrically conductive members of said electronic

component, said base member including at least one upstanding alignment member and said base including an opening therein, said upstanding alignment member adapted for passing through said opening in said base during said bringing of said compressible housing and said base member together such that said base will engage said alignment member in such a manner so as to prohibit excessive force application onto said electrically conductive members by said compressible probes..

38. (new) The test apparatus of claim 37 wherein said base defines an opening therein, said electronic component adapted for being positioned within said opening.

39. (new) The test apparatus of claim 37 wherein said base includes a plurality of apertures therein, said selected ones of said compressible probes adapted for passing through respective ones of said apertures to engage said respective ones of said electrically conductive members.

40. (new) The test apparatus of claim 37 further including a lock member movably positioned within said cover to lock said cover onto said base in a compressible manner.

41. (new) The test apparatus of claim 40 wherein said lock member is a rotational screw adapted for being screwed into said base to provide said lock of said cover onto said base.

42. (new) The test apparatus of claim 37 wherein said compressible member is a compliant pad.

43. (new) The test apparatus of claim 37 wherein said upstanding alignment member includes an adjustable member adapted for adjusting the positional relationship between said compressible housing and said base member.

44. (new) The test apparatus of claim 37 further including a conductive substrate having a plurality of conductive pads thereon, said base member adapted for being positioned on said conductive substrate such that said selected ones of said compressible probes electrically engage a respective one of said conductive pads.

45. (new) The test apparatus of claim 44 wherein said conductive substrate comprises a printed circuit board.

46. (new) The test apparatus of claim 37 wherein said structure for bringing said compressible housing and said base member together includes a pneumatically-driven member adapted for engaging said cover of said compressible housing to exert a force on said cover.

47. (new) The test apparatus of claim 46 wherein said pneumatic-driven member includes a piston.

48. (new) A method of testing an electronic component having a plurality of electrically conductive members, said method comprising:

positioning an electronic component having a plurality of electrically conductive members within a compressible housing including a base and a cover and a compressible member positioned between said base and cover and between said cover and said electronic component when said electronic component is positioned within said compressible housing;

providing a base member including a plurality of compressible probes therein, said base of said compressible housing adapted for being positioned on said base member; and

bringing said compressible housing having said electronic component therein and said base member together such that selected ones of said compressible probes engage respective ones of said electrically conductive members of said electronic component,

said base member including at least one upstanding alignment member and said base including an opening therein, said upstanding alignment member passing through said opening in said base during said bringing of said compressible housing and said base member together such that said base engages said alignment member in such a manner so as to prohibit excessive force application onto said electrically conductive members by said compressible probes..

49. (new) The method of claim 48 wherein said positioning of said electronic component comprises positioning said component on said base and locking said cover onto said base to lock said electronic component in position.

50. (new) The method of claim 48 wherein said base is provided with a plurality of apertures therein, said bringing together of said compressible housing and said base member causing selected ones of said compressible probes to pass through respective ones of said apertures prior to engaging electrically conductive members.